


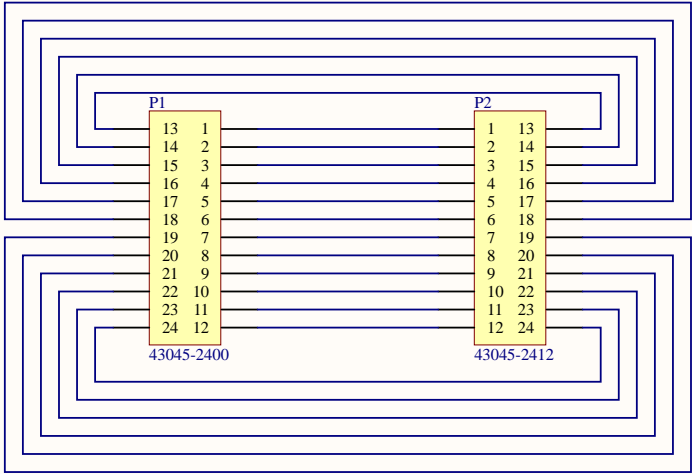
Breakout Board

Rev 1

Title <i>Breakout Board</i>			<div>Badgerloop 133 Engineering Research Building Madison, WI 53715</div> <div></div>
Size: A4	Number: 1	Revision: 1	
Date: 7/9/2020	Time: 9:15:12 PM	Sheet 1 of	
File: C:\Users\Windows PC\Desktop\Badgerloop\git_repos\hardware\breakout_board\breakout_board.SchDoc			


Badgerloop
133 Engineering Research
Building
Madison, WI 53715

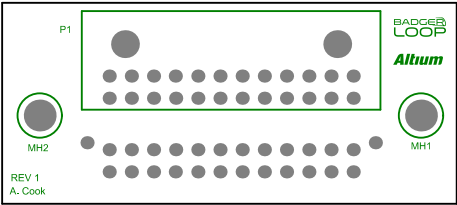
Breakout Board Connectors



MH1
4-40 Mount Hole

MH2
4-40 Mount Hole

Title Connectors		Badgerloop Electrical 133 Engineering Research Building 1500 Engineering Drive Madison, WI 53706		
Engineer: Andrew Cook	Revision:1			
Date: 7/9/2020	Time: 9:15:12 PM	Sheet2	of 1	
File: connectors.SchDoc				



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	10.00mil	4.2	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

Top Layer



Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER: Andrew Cook		TITLE: breakout_board.PcbDoc	
PCB DESIGNER: Andrew Cook			
DATE: 7/9/2020		PART NO.: Battery Module Breakout Board	REV: A
FILE NAME: breakout_board.PcbDoc		DWG NO:	SCALE: 1:1

1

2

4

A

A

B

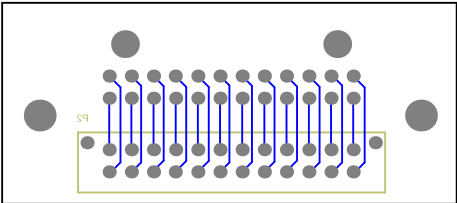
B

C

C

D

D



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	10.00mil	4.2	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

Bottom Layer

**BADGER
LOOP**

Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
Andrew Cook

PCB DESIGNER:
Andrew Cook

DATE:
7/9/2020

FILE NAME:
breakout_board.PcbDoc

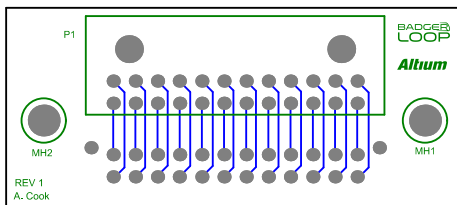
TITLE:
breakout_board.PcbDoc

PART NO.:
Battery Module Breakout Board

DWG NO:

REV:
A

SCALE:
1:1



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	10.00mil	4.2	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

Bottom Layer

Top Layer

**BADGER
LOOP**

Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER:
Andrew CookPCB DESIGNER:
Andrew CookDATE:
7/9/2020FILE NAME:
breakout_board.PcbDocTITLE:
breakout_board.PcbDocPART NO.:
Battery Module Breakout Board

DWG NO:

REV:
ASCALE:
1:1